

Product/Process Change (PCN) Notification

PCN Number: CO-10781	Contact: Elizabeth La Greca
Date Issued: October 15 th , 2015	Title: Director, Sales Operations
PCN Effective Date: December 4th, 2015	Phone: 858-795-0106
Product(s) Affected: PE42420	Email: elagreca@psemi.com
Sample Availability: November 6 th , 2015	
Change Control Board Approval #: CO-10781	
Change Category:	
☐ Wafer Fabrication Process	☐ Shipping/Labeling
☐ Design/Mask Change	☐ Equipment
Singulation Process	☐ Material
Assembly Process – New package laminate	☐ Product Specification
☐ Electrical Test	☐ Product End of Life
☐ Manufacturing Site	Other - Ordering Code
Dumage of Change	
Purpose of Change:	
Transition to an improved laminate package material for PE42420.	
Description of Change:	
Assembly supplier discontinuing current production p	rocess (electroless NiAu - ENIG) laminate plating
finish and transitioning to (electroless NiPdAu - ENEPIG), an industry standard. Peregrine is taking the	
opportunity to make this transition in order to assure ongoing laminate supply with improved	
solderability, reliability and performance.	
Reliability, form, fit or function is not affected by this change	
Beginning December 4 th , 2015 all parts shipped to the customers will be manufactured with Magnachip	
wafers in the new package laminate.	
Ordering Codes	
Original ordering code: (Magnachip + ENIG plating finish): PE42420LGBB-Z, EK42420-02	
New ordering code: (MagnaChip + ENEPIG plating finish): PE42420C-Z, EK42420-03	
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